



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Tsuga et al.

Docket No.: TI-31619

Serial No.: 10/072,073

Art Unit: 1746

Filed: 02/08/02

Examiner: Kornakov, M.

Title: Method for Removing Particles on Semiconductor Wafers

**AMENDMENT UNDER 37 CFR §1.312**

February 2, 2005

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**

I hereby certify that the above correspondence is being deposited  
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Karen Vertz  
Karen Vertz

2-2-05  
Date

This application is in condition for allowance except for the correction of formal matters. In response to the telephone conversations between the Applicant's attorney and the Examiner, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to The Examiner's requests. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.